

# PDTC143E series

NPN resistor-equipped transistors;  
 $R1 = 4.7 \text{ k}\Omega$ ,  $R2 = 4.7 \text{ k}\Omega$

Rev. 10 — 8 December 2011

Product data sheet

## 1. Product profile

### 1.1 General description

NPN Resistor-Equipped Transistor (RET) family in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package			PNP complement	Package configuration
	NXP	JEITA	JEDEC		
PDTC143EE	SOT416	SC-75	-	PDTA143EE	ultra small
PDTC143EM	SOT883	SC-101	-	PDTA143EM	leadless ultra small
PDTC143ET	SOT23	-	TO-236AB	PDTA143ET	small
PDTC143EU	SOT323	SC-70	-	PDTA143EU	very small

### 1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

### 1.3 Applications

- Digital applications in automotive and industrial segments
- Control of IC inputs
- Cost-saving alternative for BC847/857 series in digital applications
- Switching loads

### 1.4 Quick reference data

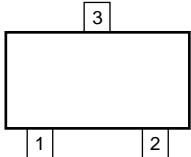
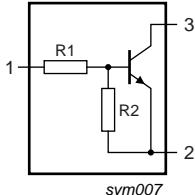
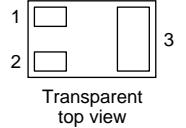
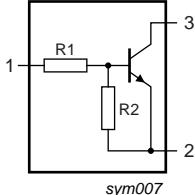
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	50	V
$I_O$	output current		-	-	100	mA
R1	bias resistor 1 (input)		3.3	4.7	6.1	$\text{k}\Omega$
R2/R1	bias resistor ratio		0.8	1	1.2	



## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
<b>SOT23; SOT323; SOT416</b>			
1	input (base)		
2	GND (emitter)		
3	output (collector)	 006aaa144	 sym007
<b>SOT883</b>			
1	input (base)		
2	GND (emitter)		
3	output (collector)	 Transparent top view	 sym007

## 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTC143EE	SC-75	plastic surface-mounted package; 3 leads	SOT416
PDTC143EM	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883
PDTC143ET	-	plastic surface-mounted package; 3 leads	SOT23
PDTC143EU	SC-70	plastic surface-mounted package; 3 leads	SOT323

## 4. Marking

Table 5. Marking codes

Type number	Marking code <sup>[1]</sup>
PDTC143EE	02
PDTC143EM	E1
PDTC143ET	*02
PDTC143EU	*02

[1] \* = placeholder for manufacturing site code

## 5. Limiting values

**Table 6. Limiting values**

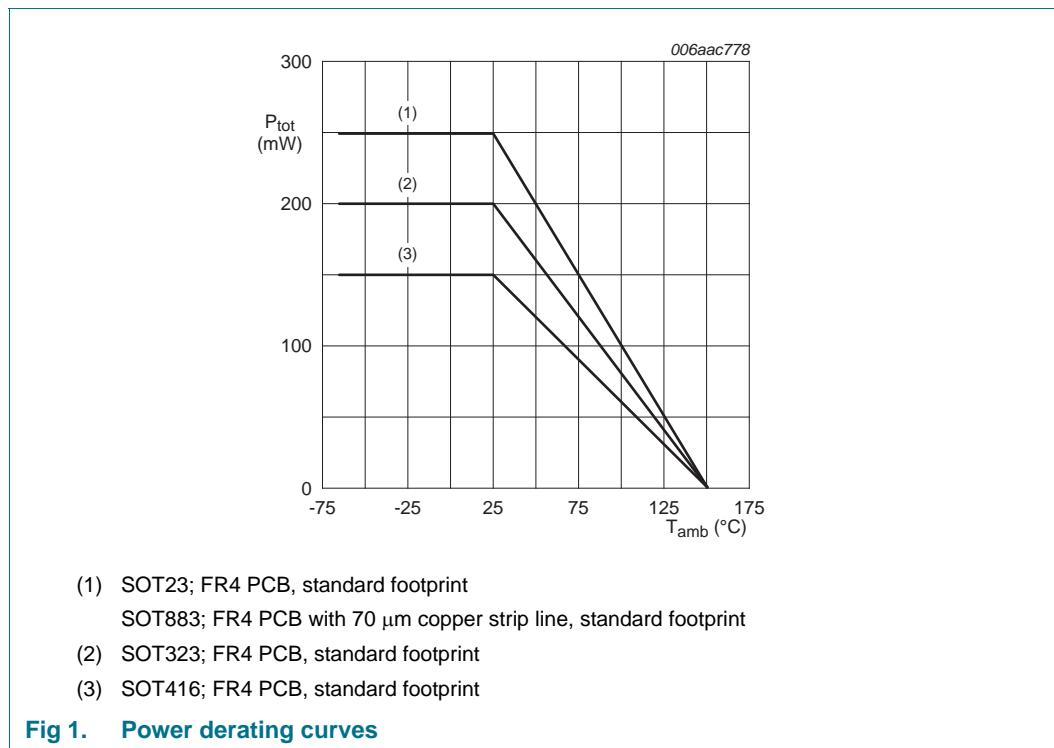
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter	-	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	10	V
V <sub>I</sub>	input voltage				
	positive		-	+30	V
	negative		-	-10	V
I <sub>O</sub>	output current		-	100	mA
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms	-	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	PDTC143EE (SOT416)	[1][2]	-	150	mW
	PDTC143EM (SOT883)	[2][3]	-	250	mW
	PDTC143ET (SOT23)	[1]	-	250	mW
	PDTC143EU (SOT323)	[1]	-	200	mW
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 70 µm copper strip line, standard footprint.



## 6. Thermal characteristics

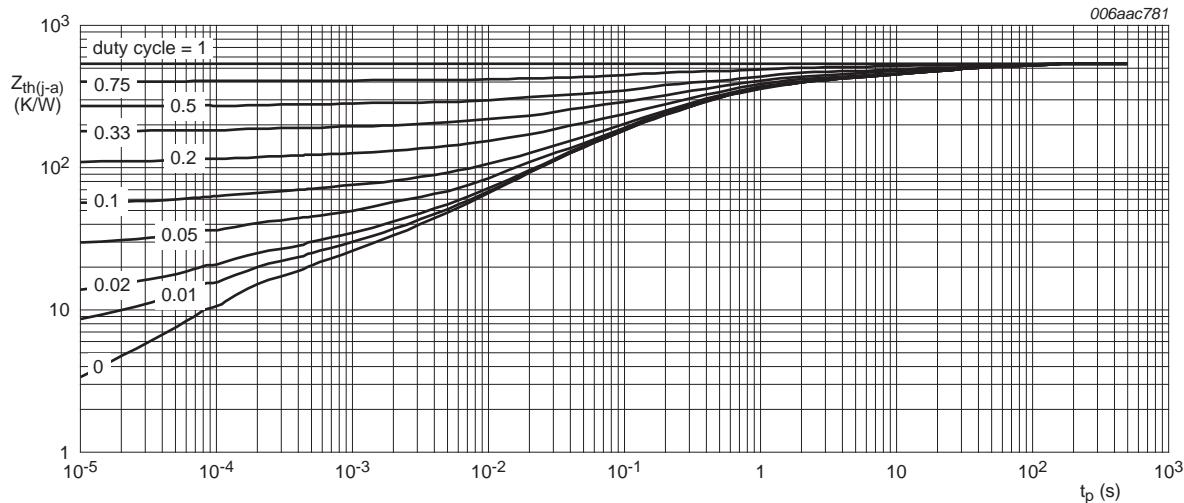
**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	PDTC143EE (SOT416)	[1][2]	-	-	830	K/W
	PDTC143EM (SOT883)	[2][3]	-	-	500	K/W
	PDTC143ET (SOT23)	[1]	-	-	500	K/W
	PDTC143EU (SOT323)	[1]	-	-	625	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

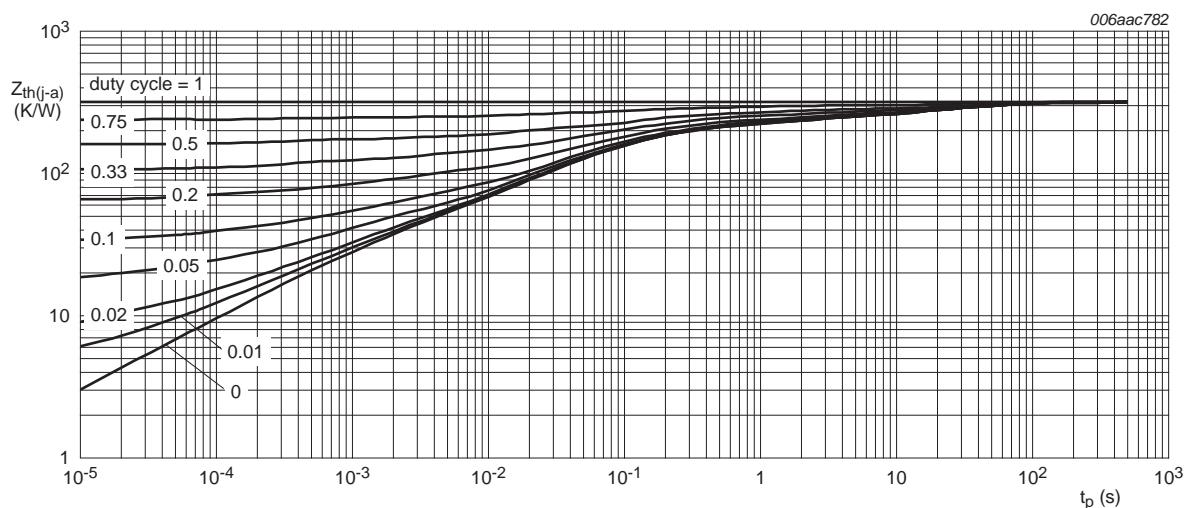
[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 70 µm copper strip line, standard footprint.



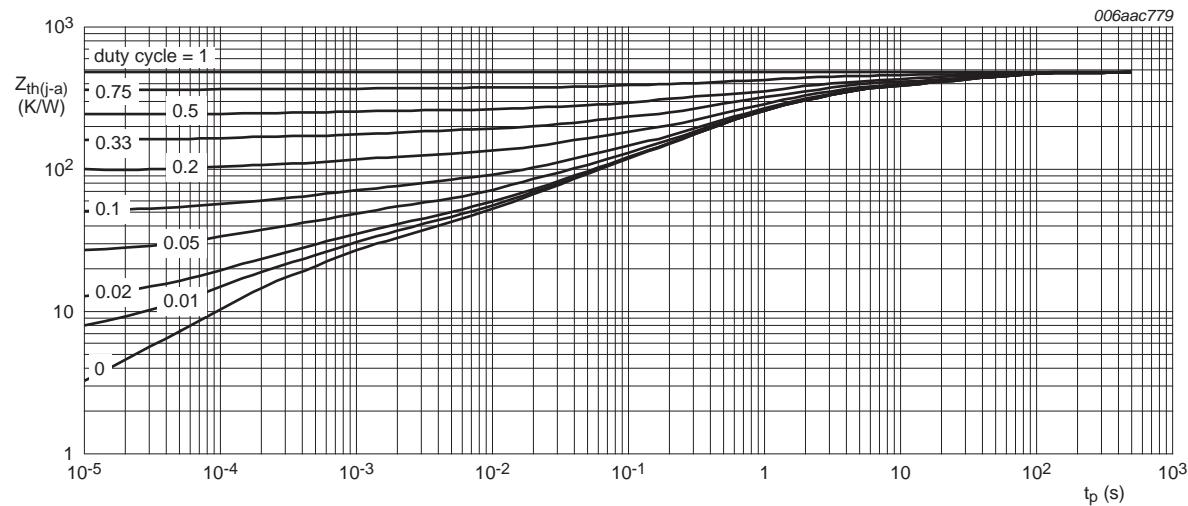
FR4 PCB, standard footprint

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for PDTC143EE (SOT416); typical values**



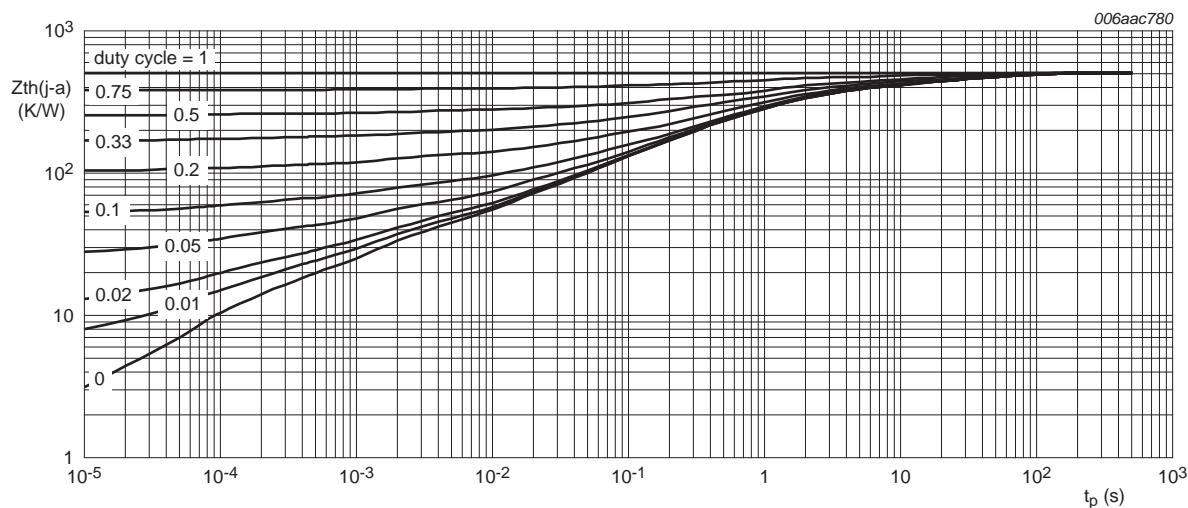
FR4 PCB, 70  $\mu$ m copper strip line

**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for PDTC143EM (SOT883); typical values**



FR4 PCB, standard footprint

**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for PDTC143ET (SOT23); typical values**



FR4 PCB, standard footprint

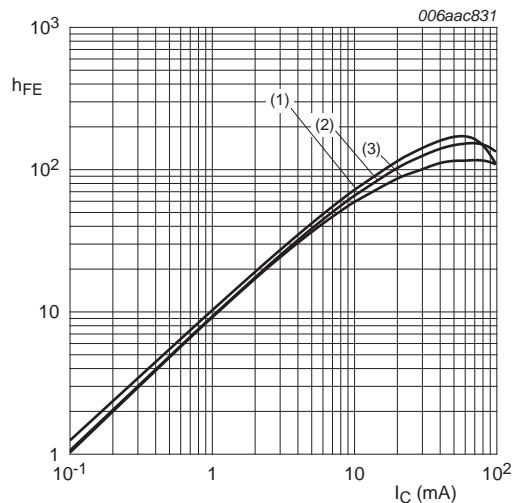
**Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for PDTC143EU (SOT323); typical values**

## 7. Characteristics

**Table 8. Characteristics** $T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

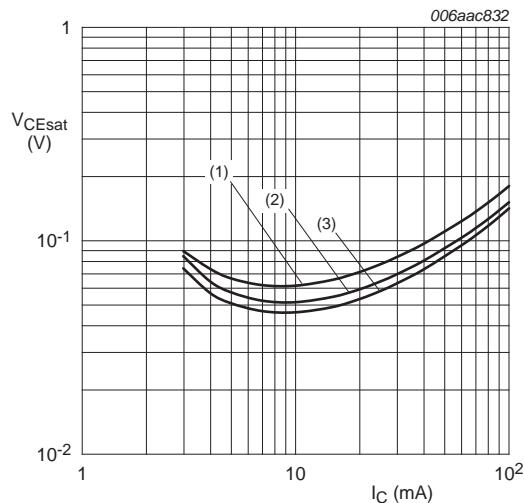
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0\text{ A}$	-	-	100	nA	
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0\text{ A}$	-	-	1	μA	
		$V_{CE} = 30\text{ V}; I_B = 0\text{ A}; T_j = 150^\circ\text{C}$	-	-	5	μA	
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	900	μA	
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}$	30	-	-		
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	-	150	mV	
$V_{I(off)}$	off-state input voltage	$V_{CE} = 5\text{ V}; I_C = 100\text{ μA}$	-	1.1	0.5	V	
$V_{I(on)}$	on-state input voltage	$V_{CE} = 0.3\text{ V}; I_C = 20\text{ mA}$	2.5	1.9	-	V	
R1	bias resistor 1 (input)		3.3	4.7	6.1	kΩ	
R2/R1	bias resistor ratio		0.8	1	1.2		
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	-	2.5	pF	
$f_T$	transition frequency	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	[1]	-	230	-	MHz

[1] Characteristics of built-in transistor



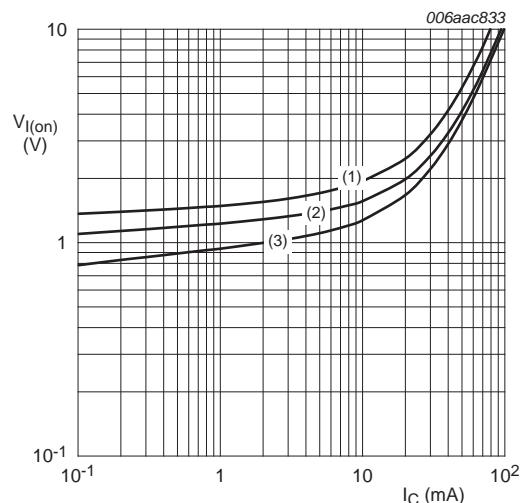
$V_{CE} = 5$  V  
(1)  $T_{amb} = 100$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = -40$  °C

**Fig 6.** DC current gain as a function of collector current; typical values



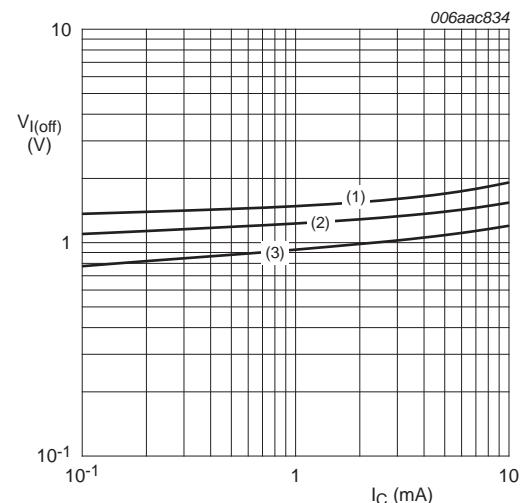
$I_C/I_B = 20$   
(1)  $T_{amb} = 100$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = -40$  °C

**Fig 7.** Collector-emitter saturation voltage as a function of collector current; typical values



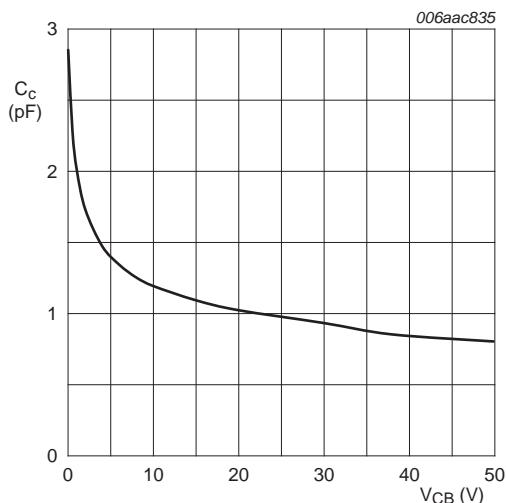
$V_{CE} = 0.3$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

**Fig 8.** On-state input voltage as a function of collector current; typical values



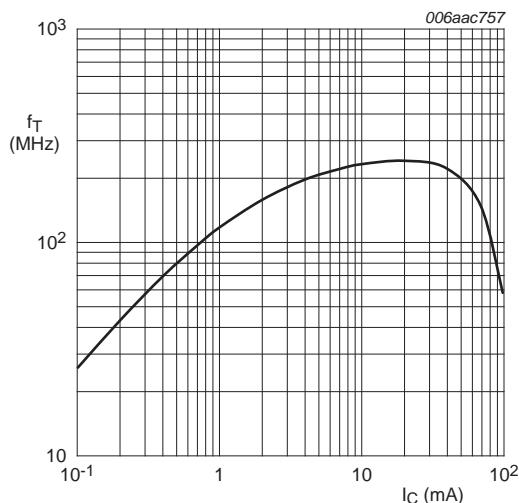
$V_{CE} = 5$  V  
(1)  $T_{amb} = -40$  °C  
(2)  $T_{amb} = 25$  °C  
(3)  $T_{amb} = 100$  °C

**Fig 9.** Off-state input voltage as a function of collector current; typical values



$f = 1$  MHz;  $T_{amb} = 25$  °C

**Fig 10. Collector capacitance as a function of collector-base voltage; typical values**



$V_{CE} = 5$  V;  $T_{amb} = 25$  °C

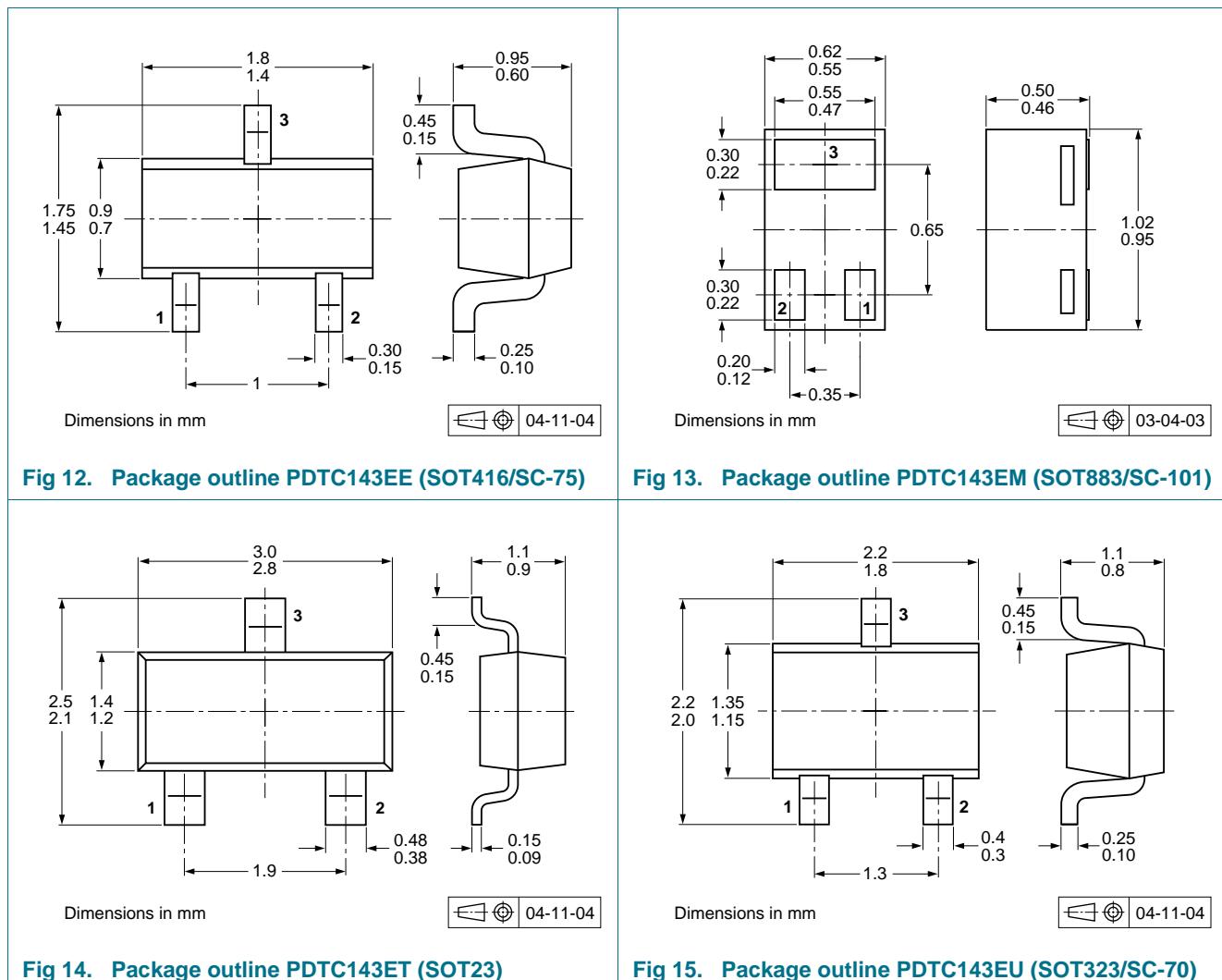
**Fig 11. Transition frequency as a function of collector current; typical values of built-in transistor**

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



## 10. Packing information

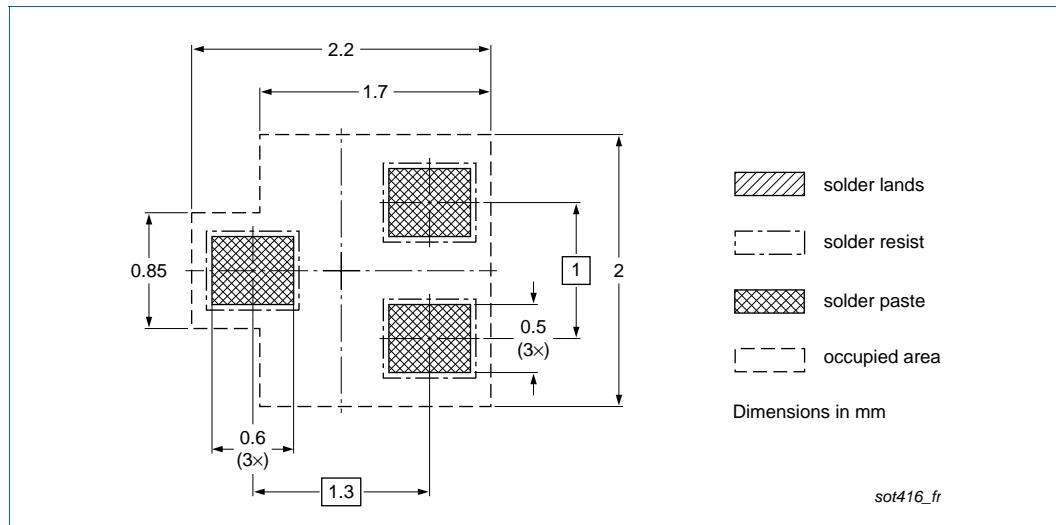
**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity		
			3000	5000	10000
PDTC143EE	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTC143EM	SOT883	2 mm pitch, 8 mm tape and reel	-	-	-315
PDTC143ET	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-235
PDTC143EU	SOT323	4 mm pitch, 8 mm tape and reel	-115	-	-135

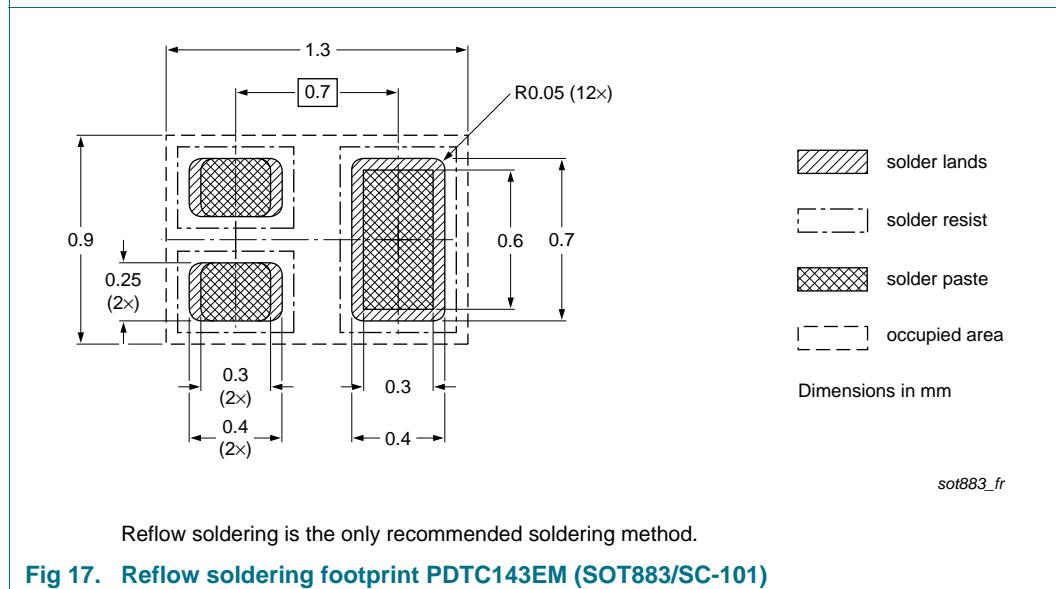
[1] For further information and the availability of packing methods, see [Section 14](#).

## 11. Soldering



Reflow soldering is the only recommended soldering method.

**Fig 16. Reflow soldering footprint PDTC143EE (SOT416/SC-75)**



Reflow soldering is the only recommended soldering method.

**Fig 17. Reflow soldering footprint PDTC143EM (SOT883/SC-101)**

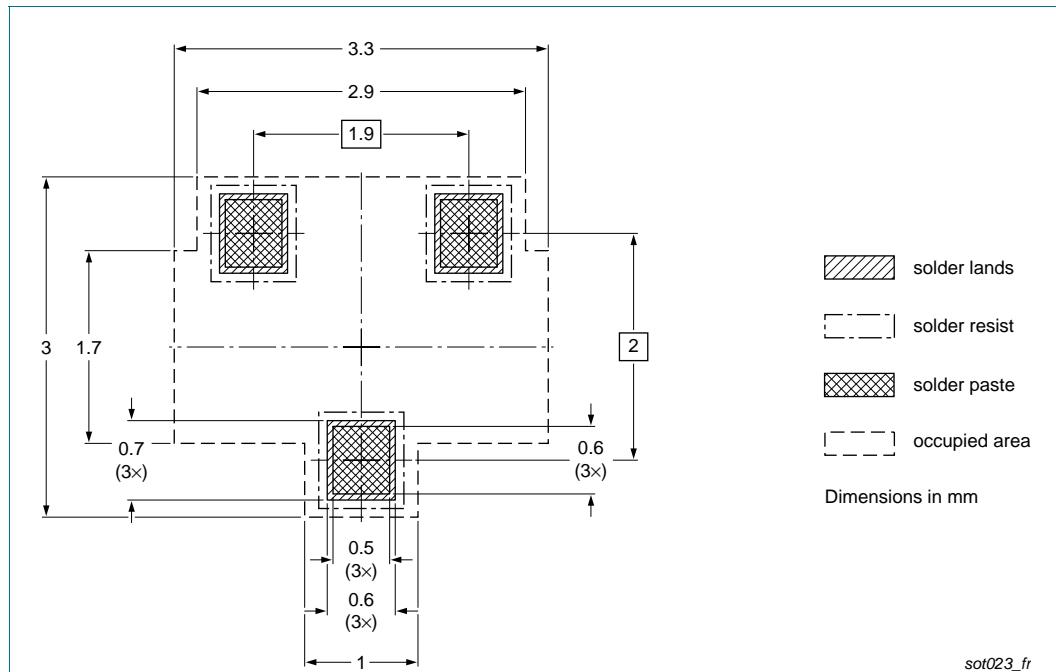


Fig 18. Reflow soldering footprint PDTC143ET (SOT23)

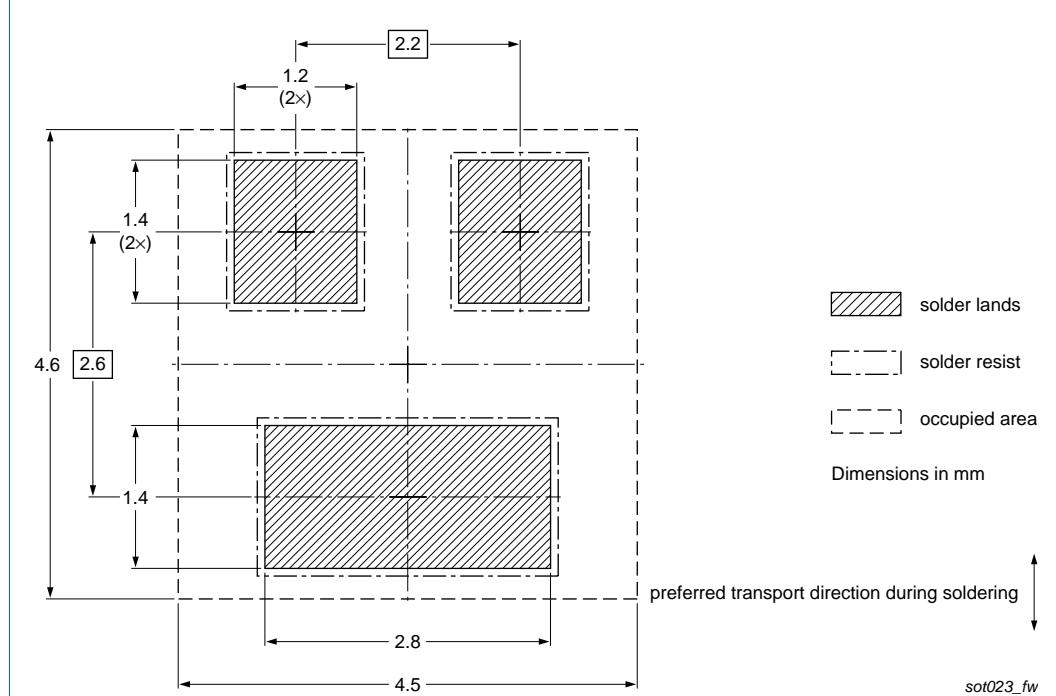


Fig 19. Wave soldering footprint PDTC143ET (SOT23)

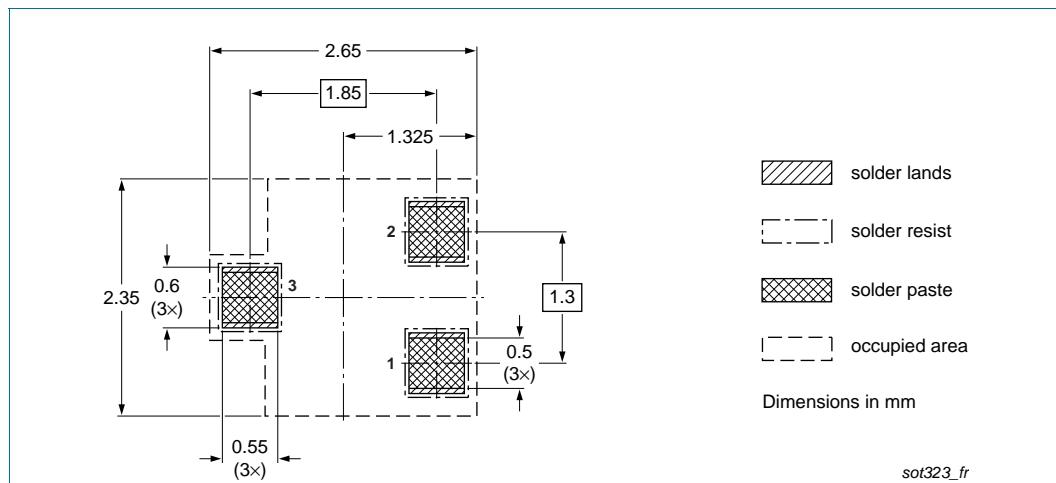


Fig 20. Reflow soldering footprint PDTC143EU (SOT323/SC-70)

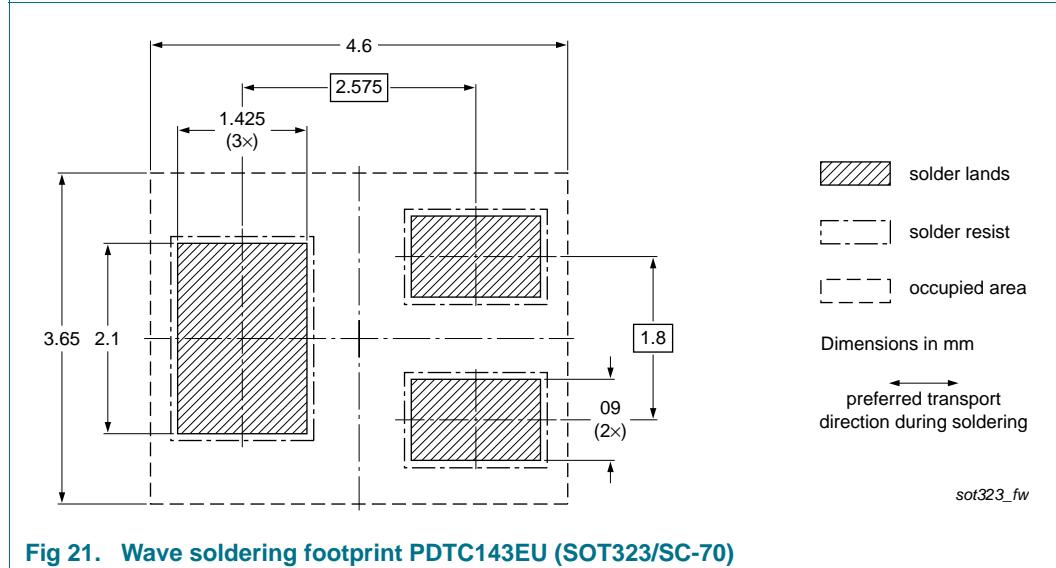


Fig 21. Wave soldering footprint PDTC143EU (SOT323/SC-70)